

Rad Hard Microelectronics Session Chairs: Cohen, Constantine**Focus:** Current activity and accomplishments in the area of RH microelectronics including supplier and DOD technology roadmaps

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[Breakout](#)

During this session the technology roadmaps of a number of suppliers of radiation hardened microelectronics will be discussed. The session will begin with a short introduction by Session Chair that will summarize the DOD activity in this area with specific emphasis on the latest activities of the Radiation Hardened Microelectronics Oversight Council (RHOC). This introduction will be followed by briefings from Honeywell, BAE Systems, Aeroflex/UTMC, Northrop-Grumman, Peregrine Semiconductor Corporation, Boeing Phantom Works, Mission Research Corporation and, finally, the Defense Microelectronics Activity.

The briefings will highlight the different technical approaches and business models adopted by each of these suppliers and, in addition, discuss a DOD initiative to address the diminished manufacturing source (DMS) problem.

Those veterans of the Radiation Hardened Microelectronics Session will certainly note the absence of some traditional participants and the inclusion of some new participants.